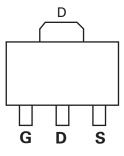


P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY							
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)				
- 60	0.058 at V _{GS} = - 10 V	- 6.5	30 nC				
- 60	0.065 at V _{GS} = - 4.5 V	- 5.5	30 110				



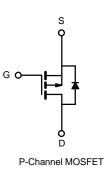
FEATURES

- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

APPLICATIONS

Load Switch





Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 60	v		
Gate-Source Voltage	V _{GS}	± 20	v		
	T _C = 25 °C		- 6.5 ^a		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 5.2	7	
Continuous Drain Current $(T_J = 150^{\circ} C)$	T _A = 25 °C	I _D	- 4.8 ^b	A	
	T _A = 70 °C		- 4.1 ^b	A	
Pulsed Drain Current	I _{DM}	- 20			
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	- 4.5		
Single Pulse Avalanche Energy	E = 0.1 mm	E _{AS}	10.1	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	6.9 ^a	Α	
Continuous Source-Drain Diode Current	T _A = 25 °C	15	3.5 ^b		
	T _C = 25 °C		10.4 ^a		
Maximum Power Dissipation	T _C = 70 °C	PD	6.6 ^a	w	
Maximum Power Dissipation	T _A = 25 °C	' D	2.1 ^b	vv	
	T _A = 70 °C		1.1 ^b		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	33	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.98	1.2			

Notes:

a. Based on $T_C = 25 \ ^{\circ}C$.

b. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V$, $I_D = -250 \mu A$	- 60			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μΑ		68		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250 \mu A$		- 5.2		mv/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.2		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zara Cata Valtaga Drain Current		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μA
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 25			Α
	Р	V _{GS} = - 10 V, I _D = - 3 A		0.058		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -2 \text{ A}$		0.065		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A	20			S
Dynamic ^b				•		
Input Capacitance	C _{iss}			1500		
Output Capacitance	C _{oss}	V_{DS} = - 25 V, V_{GS} = 0 V, f = 1 MHz		200		pF
Reverse Transfer Capacitance	C _{rss}			150		
Tatal Cata Charge	Qg	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = -10 \text{ V}, \text{ I}_{D} = -5 \text{ A}$		38	56	nC
Total Gate Charge				19	30	
Gate-Source Charge	Q _{gs}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5 \text{ A}$		9		
Gate-Drain Charge	Q _{gd}			10		1
Gate Resistance	Rg	f = 1 MHz		5.2		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	V_{DD} = - 2 V, R_L = 2 Ω		7	15	ns
Turn-Off Delay Time	t _{d(off)}	${\rm I}_{\rm D}\cong$ - 5 A, ${\rm V}_{\rm GEN}$ = - 10 V, ${\rm R}_{\rm g}$ = 1 Ω		70	110	
Fall Time	t _f			40	60	
Drain-Source Body Diode Characteristic	s					
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			- 6.9	A
Pulse Diode Forward Current ^a	I _{SM}				- 15	
Body Diode Voltage	V _{SD}	I _S = - 3 A		- 1	- 1.5	V
Body Diode Reverse Recovery Time	t _{rr}			45	68	ns
Body Diode Reverse Recovery Charge	Q _{rr}			59	120	nC
Reverse Recovery Fall Time t _a		I _F = - 5 A, di/dt = 10 A/μs, T _J = 25 °C		29		
Reverse Recovery Rise Time	t _b			16		ns

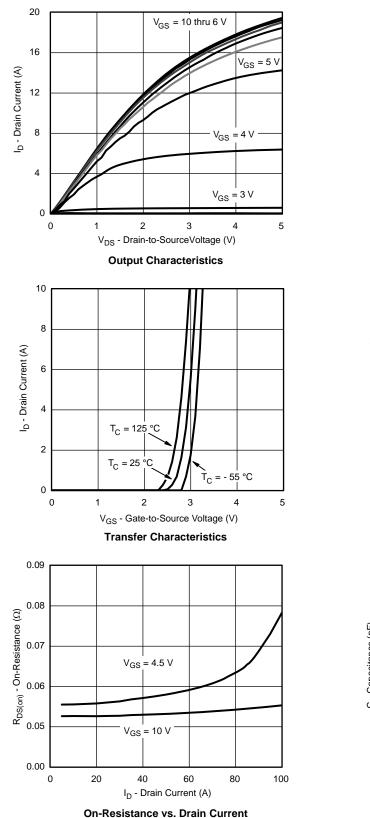
Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

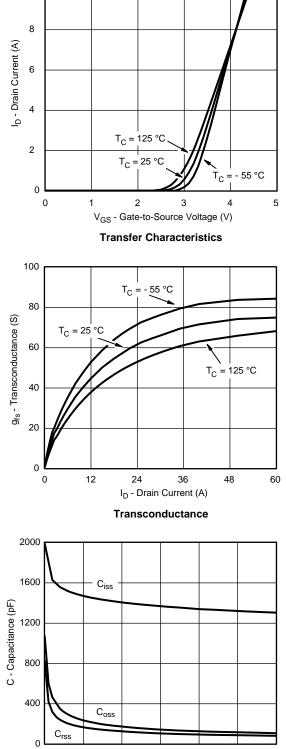
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



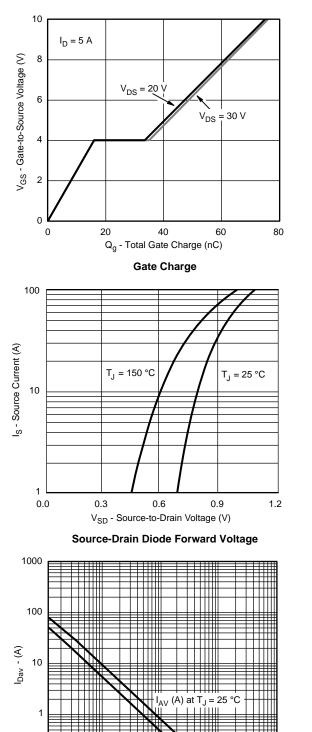


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



V_{DS} - Drain-to-Source Voltage (V) Capacitance





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

 $\label{eq:Tin-s} T_{\text{in}} \text{-} (s)$ Single Pulse Avalanche Current Capability vs. Time

0.01

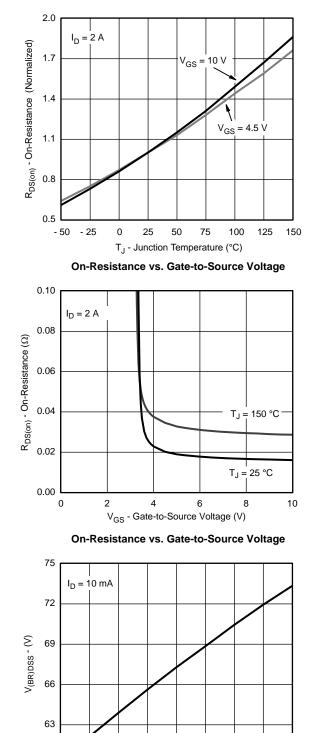
0.1

1

11111

 I_{AV} (A) at T_{J} = 150

0.001



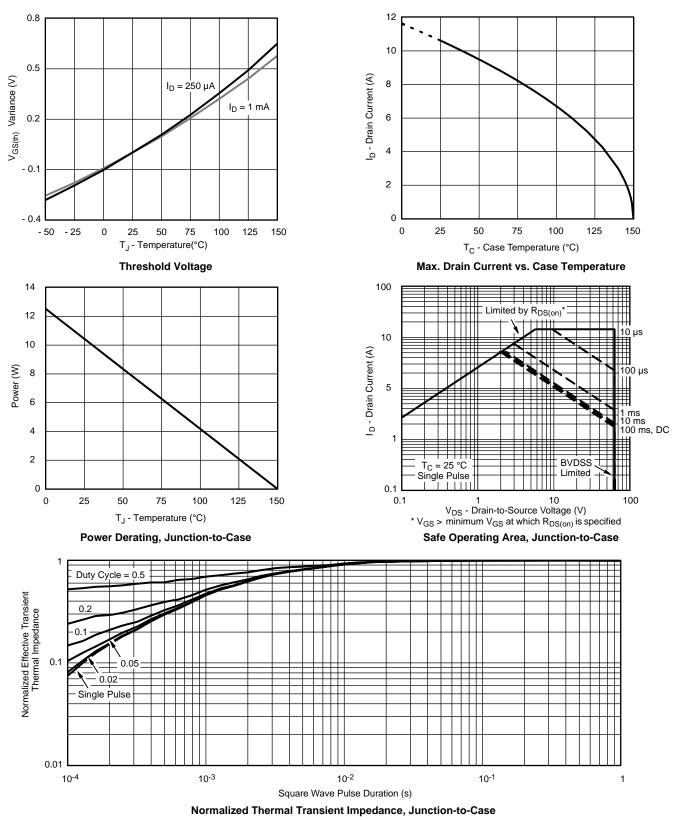
60 - 50 - 25 0 25 50 75 100 125 150 T_J - Temperature (°C)

Drain-Source Breakdown Voltage vs. Junction Temperature

0.1

0.0001

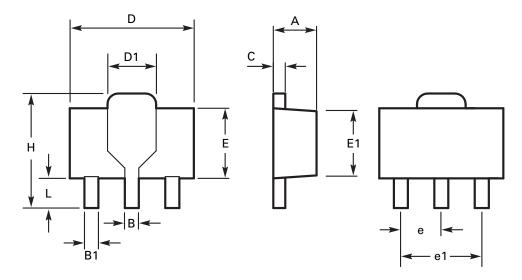




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Package outline - SOT89



DIM	Millimeters		Inc	hes	DIM	Millimeters		Inc	hes
	Min	Max	Min	Max		Min	Max	Min	Max
А	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		3.00 BSC 0.118 BSC	
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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